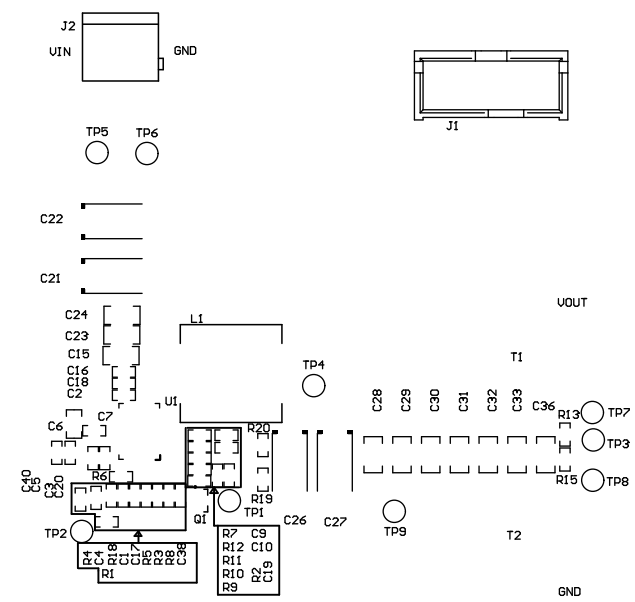
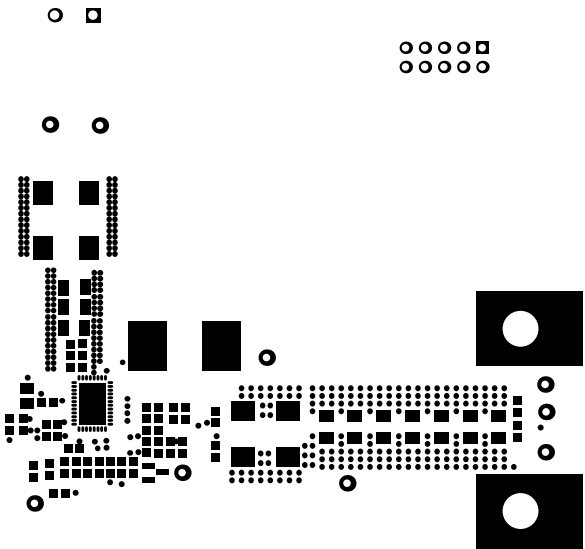
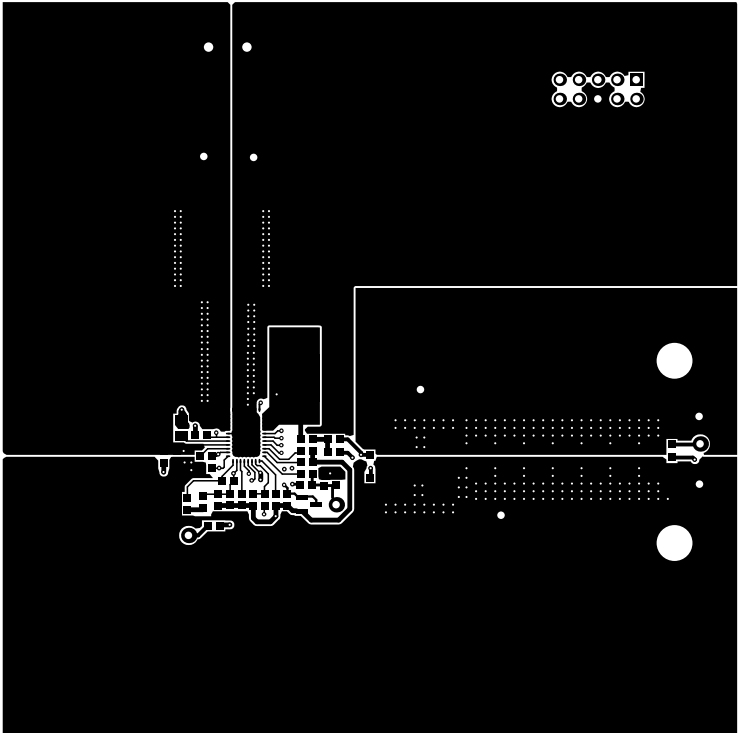




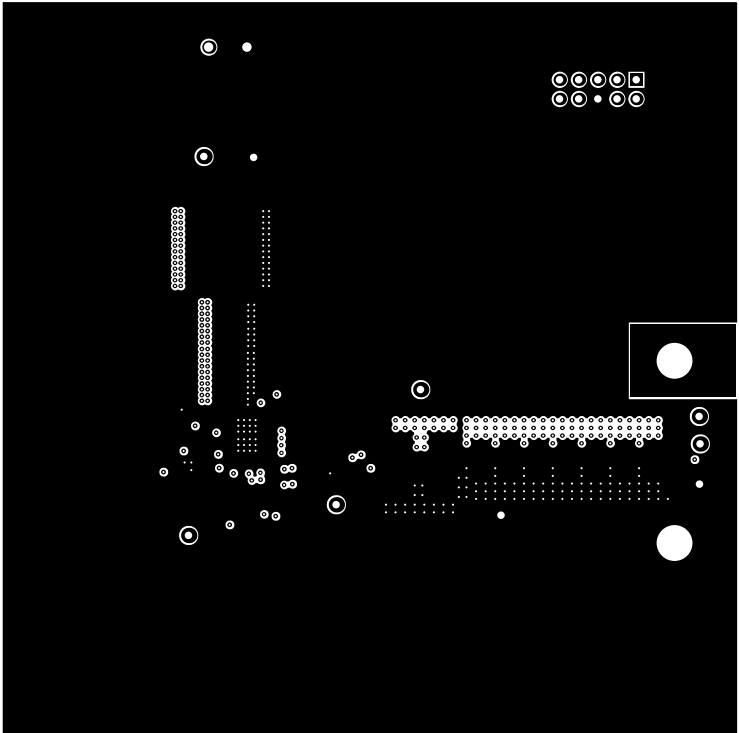
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP4499	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Top Overlay			
PLOT NAME = Top Overlay	GENERATED : 4/11/2016 11:15:28 AM		TEXAS INSTRUMENTS



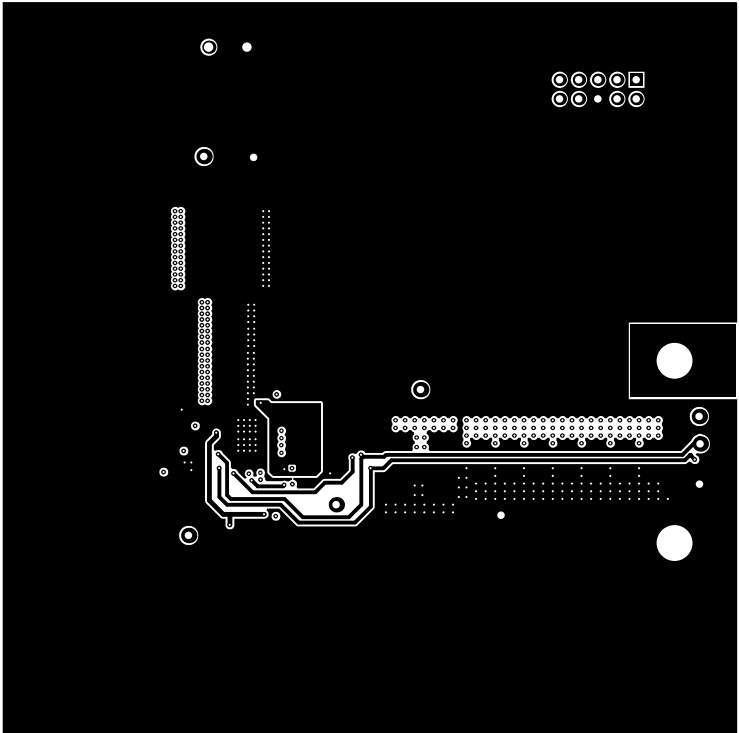
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP4499	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Top Solder			
PLOT NAME = Top Solder Mask	GENERATED : 4/11/2016 11:15:28 AM	TEXAS INSTRUMENTS	



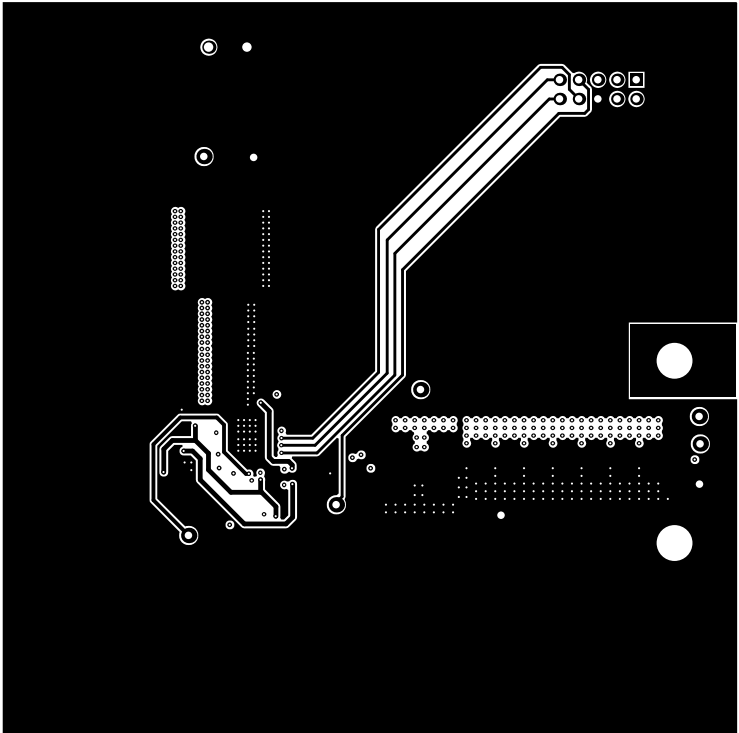
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP4499	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Top Layer			
PLOT NAME = Top Layer	GENERATED : 4/11/2016 11:15:29 AM	TEXAS INSTRUMENTS	



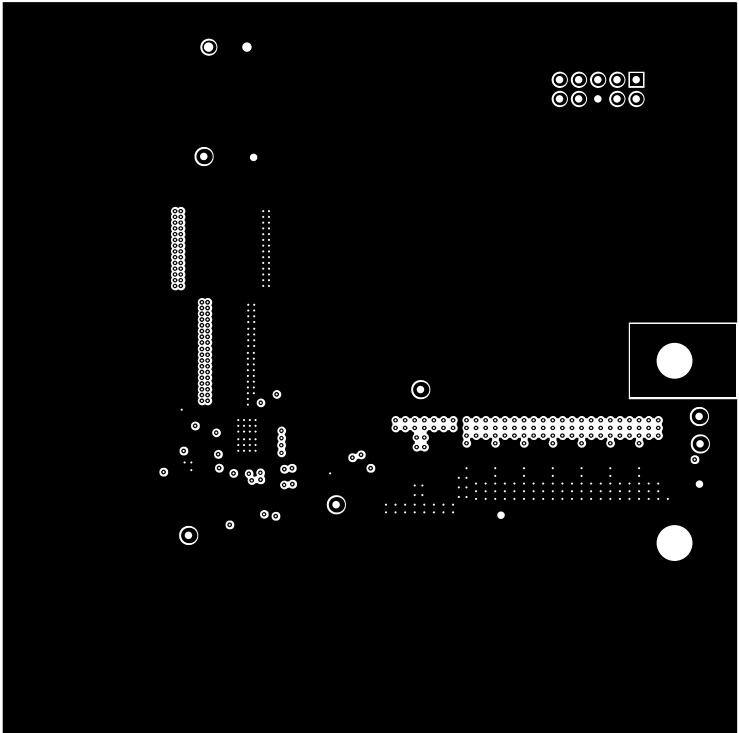
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP4499	REV: A	SUN REV: Not In VersionControl
LAYER NAME =			
PLOT NAME = Signal Layer 1	GENERATED : 4/11/2016 11:15:30 AM	TEXAS INSTRUMENTS	



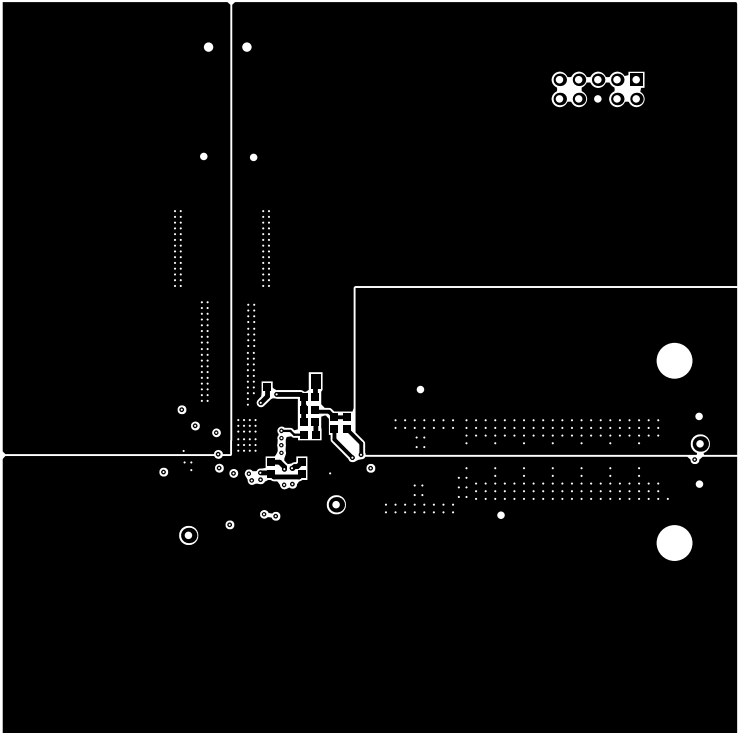
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP4499	REV: A	SUN REV: Not In VersionControl
LAYER NAME =			
PLOT NAME = Signal Layer 2	GENERATED : 4/11/2016 11:15:30 AM	TEXAS INSTRUMENTS	



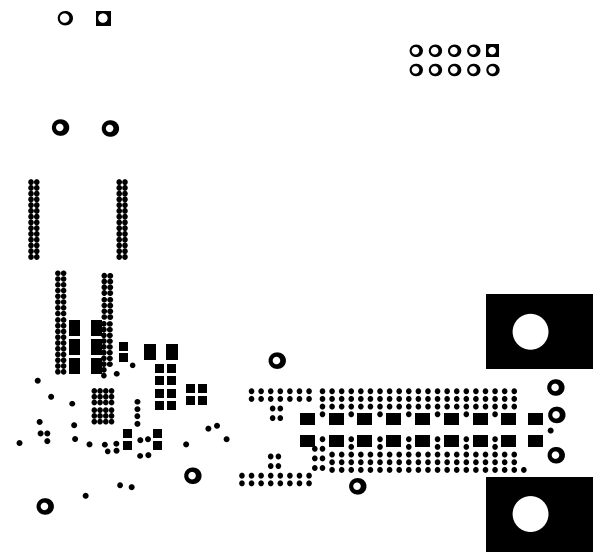
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP4499	REV: A	SUN REV: Not In VersionControl
LAYER NAME =			
PLOT NAME = Signal Layer 3	GENERATED : 4/11/2016 11:15:31 AM	TEXAS INSTRUMENTS	



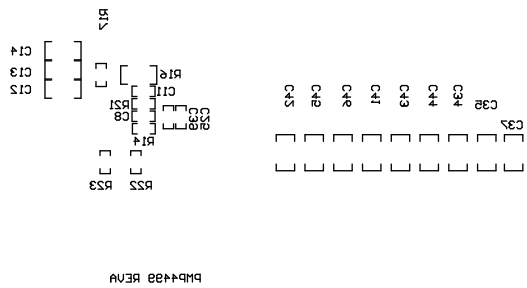
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP4499	REV: A	SUN REV: Not In VersionControl
LAYER NAME =			
PLOT NAME = Signal Layer 4	GENERATED : 4/11/2016 11:15:32 AM	TEXAS INSTRUMENTS	



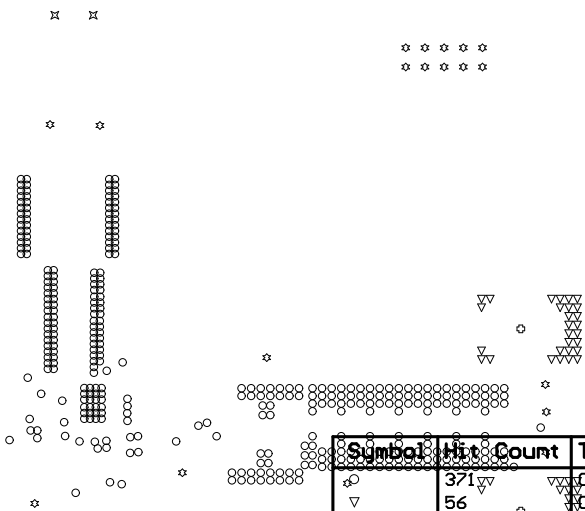
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP4499	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Bottom Layer			
PLOT NAME = Bottom Layer	GENERATED : 4/11/2016 11:15:32 AM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP4499	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Bottom Solder			
PLOT NAME = Bottom Solder Mask	GENERATED : 4/11/2016 11:15:33 AM	TEXAS INSTRUMENTS	



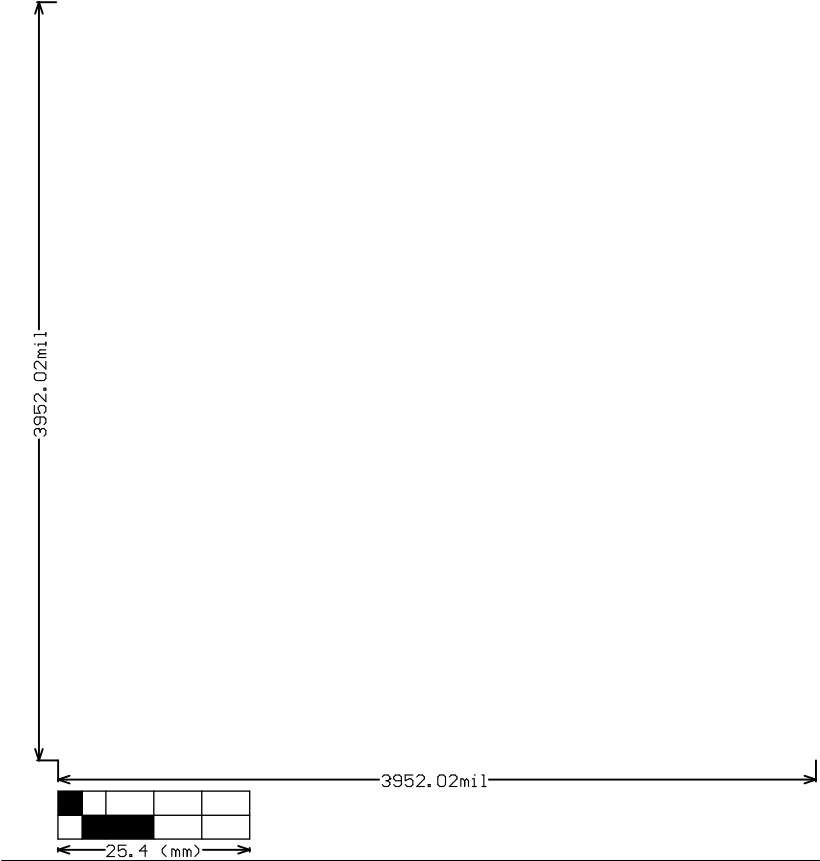
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP4499	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Bottom Overlay			
PLOT NAME = Bottom Overlay	GENERATED : 4/11/2016 11:15:34 AM	TEXAS INSTRUMENTS	



Symbol	Hit Count	Tool Size	Plated	Hole Type
⊙	371	0.305mm (12mil)	PTH	Round
▽	56	0.406mm (16mil)	PTH	Round
☆	19	1.016mm (40mil)	PTH	Round
⊠	2	1.25mm (49.213mil)	PTH	Round
⊕	2	4.775mm (188mil)	PTH	Round
450 Total				

Drill Table

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP4499	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Drill Drawing			
PLOT NAME = Drill Drawing	GENERATED : 4/11/2016 11:15:35 AM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP4499	REV: A	SUN REV: Not In VersionControl
LAYER NAME = M2 Board Dimensions			
PLOT NAME = Board Dimensions	GENERATED : 4/11/2016 11:15:35 AM	TEXAS INSTRUMENTS	

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